



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



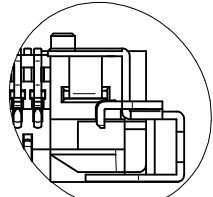
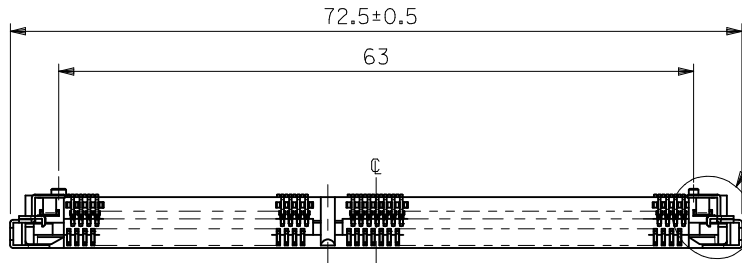
Contact us

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Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



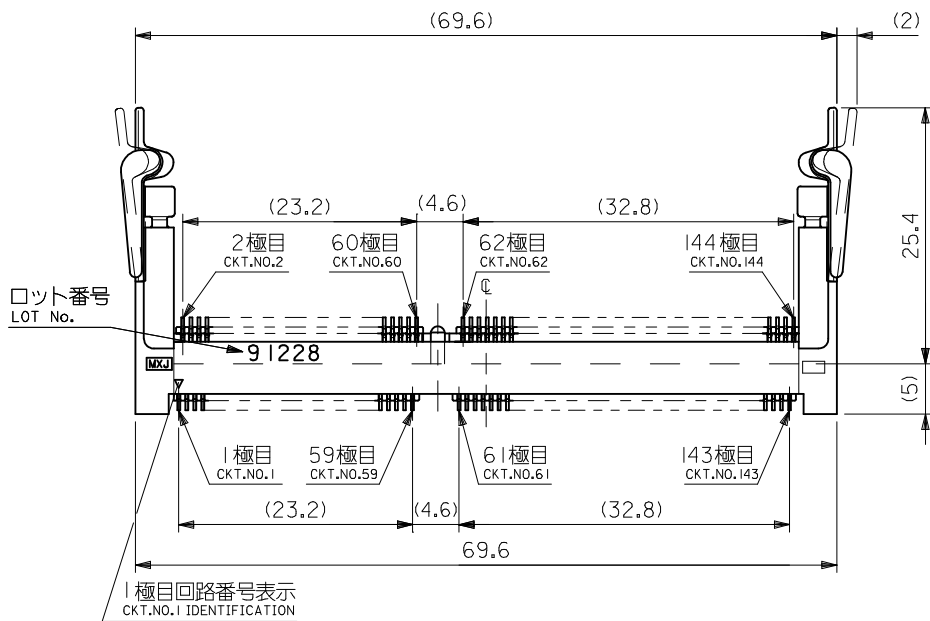


詳細 D
DETAIL D
(SCALE 5:1)

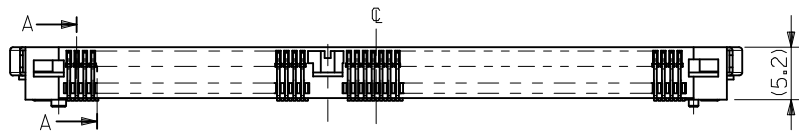
注記 NOTES
1. 材料 MATERIAL
ハウジング : ガラス入り耐熱樹脂、白色、UL94V-0
HOUSING : G.F.HEAT RESISTANT PLASTIC, WHITE, UL94V-0
ターミナル : 燐青銅
TERMINAL : PHOSPHOR BRONZE
ネイル : 黄銅
NAIL : BRASS

2. めっき仕様 PLATING
ロングターミナル LONG TERMINAL
接点部 : 金めっき 0.25µmMIN.
CONTACT AREA : GOLD 0.25 MICROMETER MINIMUM.
半田付け部 : 錫めっき 1.0µmMIN.
SOLDER TAIL AREA : TIN 1.0 MICROMETER MINIMUM.
下地めっき : ニッケルめっき 2.0µmMIN.
UNDER-PLATING : NICKEL 2.0 MICROMETER MINIMUM.
ショートターミナル SHORT TERMINAL
接点部 : 金めっき 0.25µmMIN.
CONTACT AREA : GOLD 0.25 MICROMETER MINIMUM.
半田付け部 : 錫めっき 1.0µmMIN.
SOLDER TAIL AREA : TIN 1.0 MICROMETER MINIMUM.
下地めっき : ニッケルめっき 2.0µmMIN.
UNDER-PLATING : NICKEL 2.0 MICROMETER MINIMUM.
ネイル NAIL
錫めっき : 1.0µmMIN.
TIN : 1.0 MICROMETER MINIMUM.
下地めっき : ニッケルめっき 1.0µmMIN.
UNDER-PLATING : NICKEL 1.0 MICROMETER MINIMUM.

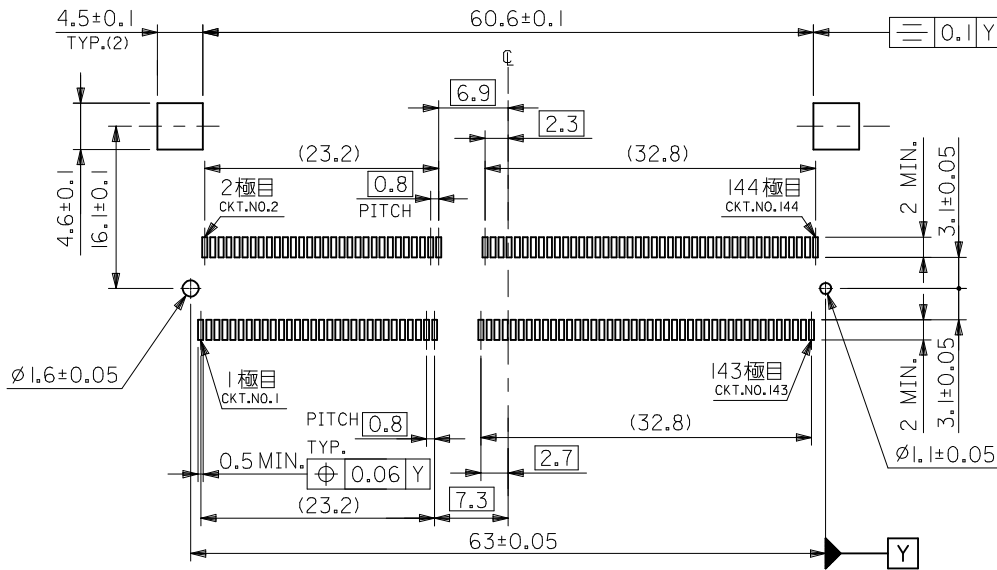
3. テール平坦度は、0.1 MAX. とする。
TAIL COPLANARITY TO BE 0.1 MAX.
ネイル平坦度は、0.1 MAX. とする。
NAIL COPLANARITY TO BE 0.1 MAX.
4. 本製品は54698-144*の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 54698-144*.



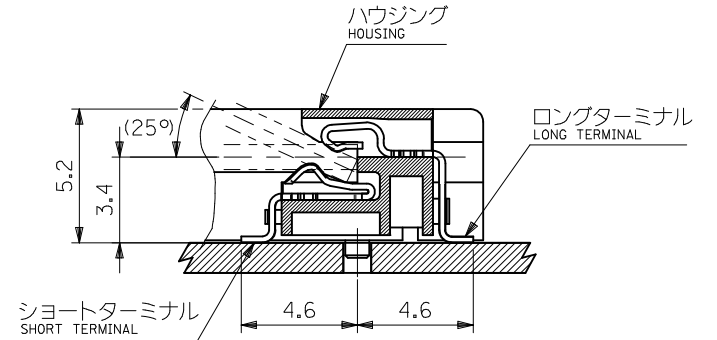
1.75	2.85	1.35	3.25	4.05	***V	ハードトレイ (高さ9)	54698-7008	54698-700*
						ハードトレイ (高さ11)	54698-7005	
		標準トレイ	54698-7002					
3.25	1.35	2.85	1.75	5.55	5.0V	ハードトレイ (高さ9)	54698-7007	
						ハードトレイ (高さ11)	54698-7004	
		標準トレイ	54698-7001					
2.5	2.1	2.1	2.5	4.8	3.3V	ハードトレイ (高さ11)	54698-7003	
						標準トレイ	54698-7000	
		パッケージ	MATERIAL NO.	MODEL NO.				



REVISED EC NO. J2013-0247 2012/08/28 DRWN:Y0010 2012/08/28 CHKD:MTOMITA 2012/08/28 APPR:Y0110 2012/08/28	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 2:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		10 UNDER	±0.2	DRAWN BY MNAGATA	DATE 2004/05/14	TITLE 0.8MM PITCH S.O.DIMM SOCKET 144CKT,H=5.2 -LEAD FREE-			
		10 OVER 30 UNDER	±0.25	CHECKED BY KTOJO	DATE 2004/05/14				
		30 OVER	±0.3	APPROVED BY MSASAO	DATE 2004/05/14				
ANGULAR ±3 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE CHART		DOCUMENT NO. SD-54698-004		SHEET NO. 1 OF 3	
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION									

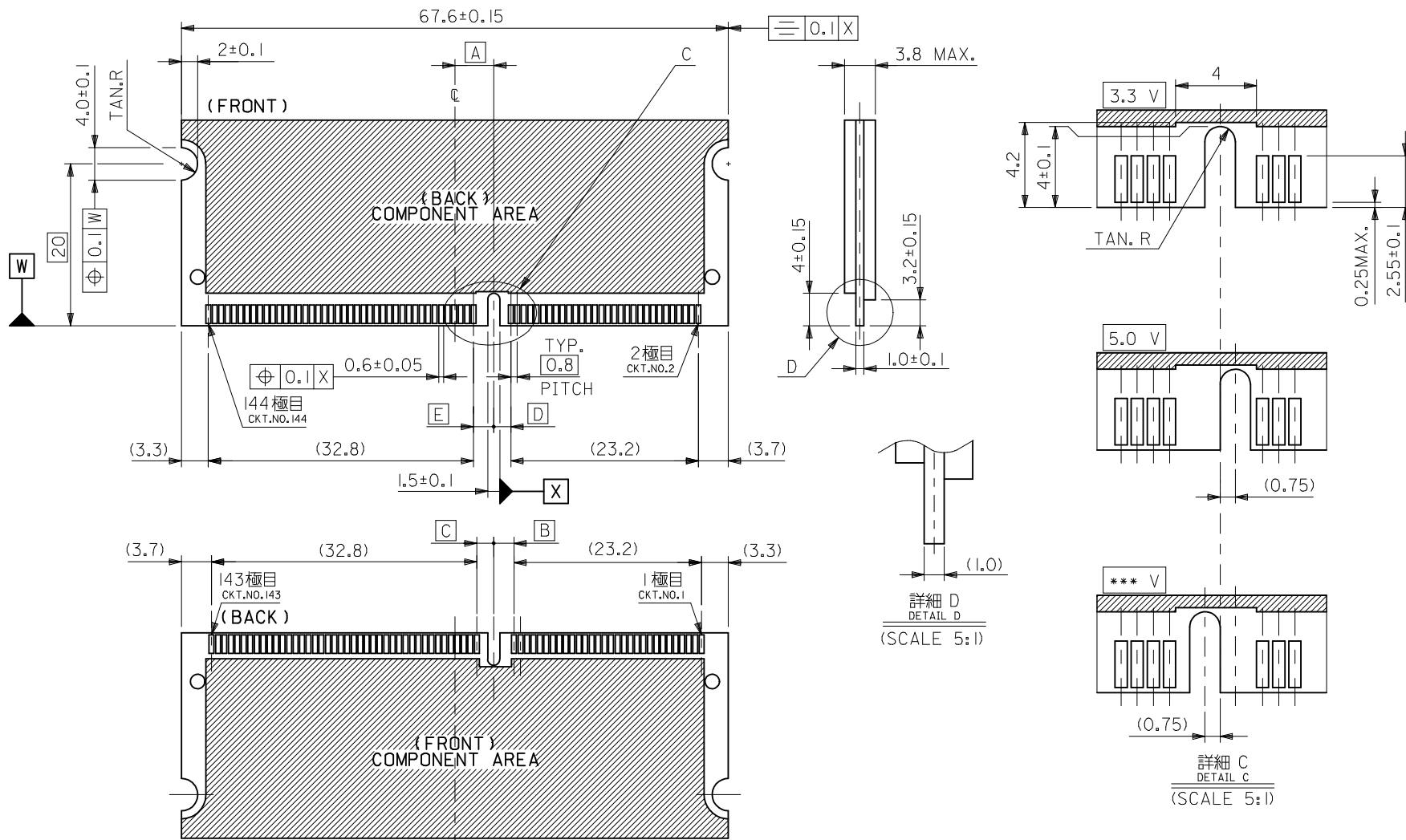


推奨基板寸法
RECOMMENDED PCB PATTERN LAYOUT
(THK: 1.2±0.1)



断面 A-A
SECTION A-A
(SCALE 5:1)

REVISED EC NO.: J2013-0247 DRWN: YGOTO CHKD: M TOMITA APPR: Y ITO 2012/08/28 2012/08/28 2012/08/28	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE 2:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY MNAGATA	DATE 2004/05/14	TITLE 0.8MM PITCH S.O.DIMM SOCKET 144CKT,H=5.2 -LEAD FREE-	
	10 OVER 30 UNDER	±0.25	CHECKED BY KTOJO	DATE 2004/05/14	molex DOCUMENT NO. SD-54698-004 SHEET NO. 2 OF 3	
	30 OVER	±0.3	APPROVED BY MSASAO	DATE 2004/05/14		
ANGULAR ±3°	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE CHART			
			SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		



推奨基板寸法
RECOMMENDED MATING BOARD CONFIGURATION
(THK: 1.0±0.1)

REVISED EC NO: J2013-0247 DRWN: YG010 CHKD: M TOMITA APPR: Y0110 2012/08/28 2012/08/28 2012/08/28	DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE 2:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
		10 UNDER	±0.2	DRAWN BY MNAGATA	DATE 2004/05/14	TITLE	0.8MM PITCH S.O.DIMM SOCKET 144CKT:H=5.2 -LEAD FREE-
		10 OVER 30 UNDER	±0.25	CHECKED BY KTOJO	DATE 2004/05/14	molex	
		30 OVER	±0.3	APPROVED BY MSASAO	DATE 2004/05/14		DOCUMENT NO. SD-54698-004
ANGULAR ±3 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		